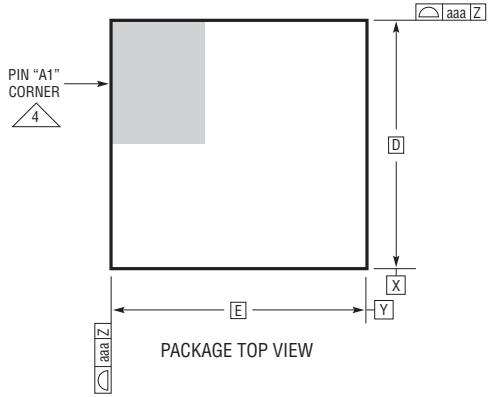
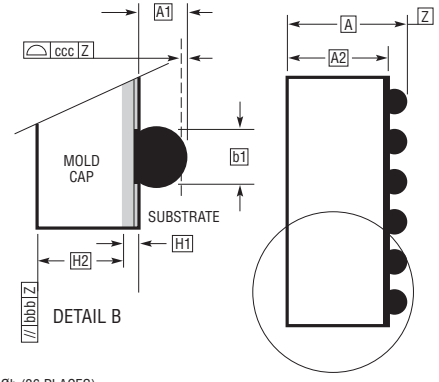
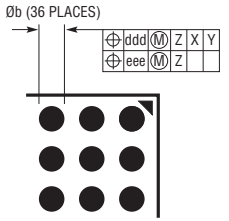
BGA Package
36-Lead (6.25mm × 6.25mm × 2.32mm)
(Reference LTC DWG # 05-08-1998 Rev Ø)



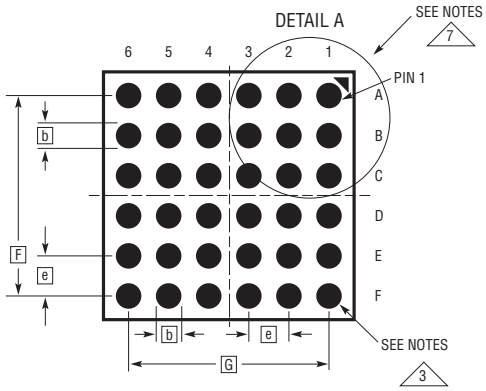
PACKAGE TOP VIEW



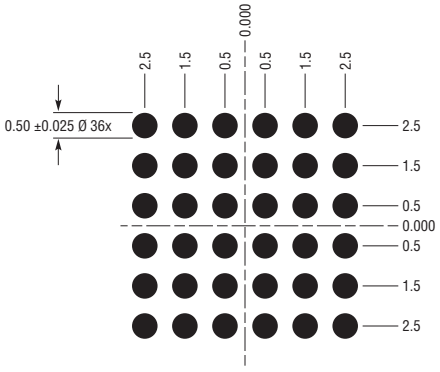
DETAIL B
PACKAGE SIDE VIEW



DETAIL A



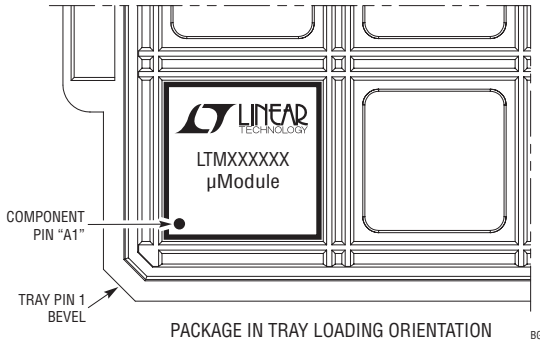
PACKAGE BOTTOM VIEW



SUGGESTED PCB LAYOUT
TOP VIEW

DIMENSIONS				
SYMBOL	**MIN**	**NOM**	**MAX**	**NOTES**
A	2.12	2.32	2.52	
A1	0.40	0.50	0.60	
A2	1.72	1.82	1.92	
b	0.50	0.60	0.70	
b1	0.47	0.50	0.53	
D		6.25		
E		6.25		
e		1.00		
F		5.00		
G		5.00		
H1	0.27	0.32	0.37	
H2	1.45	1.50	1.55	
aaa			0.15	
bbb			0.10	
ccc			0.20	
ddd			0.25	
eee			0.10	
TOTAL NUMBER OF BALLS: 36				

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS
3. BALL DESIGNATION PER JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION IS 96.5% Sn/3.0% Ag/0.5% Cu
7. PACKAGE ROW AND COLUMN LABELING MAY VARY AMONG µModule PRODUCTS. REVIEW EACH PACKAGE LAYOUT CAREFULLY



PACKAGE IN TRAY LOADING ORIENTATION

BGA 36 0215 REV Ø